PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
CHUNLIN KE	07/19/2017

RECEIVING PARTY DATA

Name:	TENCENT TECHNOLOGY (SHENZHEN) COMPANY LIMITED	
Street Address:	35/F, TENCENT BLD., KEJIZHONGYI ROAD	
Internal Address:	MIDWEST DISTRICT OF HI-TECH PARK, NANSHAN DISTRICT	
City:	SHENZHEN, GUANGDONG	
State/Country:	CHINA	
Postal Code:	518057	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14794084

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	013422-0075-999
NAME OF SUBMITTER:	DANIEL H. MAO
SIGNATURE:	/Daniel H. Mao/
DATE SIGNED:	07/24/2017

Total Attachments: 1

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PATENT 504471059 REEL: 043083 FRAME: 0247

ASSIGNMENT

WHEREAS, I, CHUNLIN KE, a citizen of the People's Republic of China, having a mailing address of 35/F, Tencent Building, Kejizhongyi Road, Midwest District of Hi-tech Park, Nanshan District, Shenzhen, Guangdong 518057, PRC, and residing in Shenzhen, Guangdong, PRC, ASSIGNOR, am the inventor of the invention in "SYSTEMS AND METHODS FOR MULTI-DEVICE INTERACTION" for which an application for a Patent of the United States has been filed

- which is identified by Jones Day docket no. 013422-0075-999
- which was filed on July 8, 2015, Application No. 14/794,084

and WHEREAS, TENCENT TECHNOLOGY (SHENZHEN) COMPANY LIMITED, a corporation organized and existing under the laws of People's Republic of China, and having an office for the transaction of business at 35/F, Tencent Building, Kejizhongyi Road, Midwest District of Hi-tech Park, Nanshan District, Shenzhen, Guangdong 518057, PRC, ASSIGNEE, is desirous of obtaining our entire right, title and interest in, to and under the said invention and the said application:

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I, the ASSIGNOR, have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, my entire right, title and interest in, to and under the said invention, and the said United States application and all divisions, renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may be filed for said invention in any country or countries foreign to the United States, together with the right to file such applications and the right to claim for the same the priority rights derived from said United States application under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application is filed, as may be applicable; and all forms of industrial property protection, including, without limitation, patents, utility models, inventors' certificates and designs which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof; and all right to sue for infringement including past infringement;

AND I HEREBY authorize and request the Commissioner for Patents and any Official of any country or countries foreign to the United States, whose duty it is to issue patents or other evidence or forms of industrial property protection on applications as aforesaid, to issue the same to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I HEREBY covenant and agree that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith.

AND I HEREBY further covenant and agree that I will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and foreign applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention in all countries.

IN TESTIMONY WHEREOF, I hereunto set my hand and seal the day and year set opposite my signature.

Date 19th, July, 2017 CHUNLIN KE L.S

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